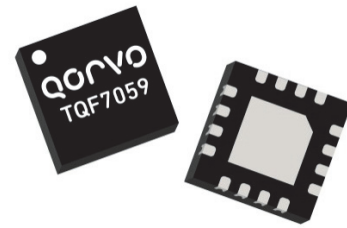


General Description

The TQF7059 is a fully integrated WLAN front-end module (FEM) designed for 802.11ac applications. The TQF7059 contains a 5 GHz power amplifier, a power detector, a front-end SPDT switch, and an LNA with bypass mode. The architecture and interface are optimized to provide outstanding stable performance across temperature and voltage range for next generation, high throughput 802.11ac WLAN applications.

The TQF7059 FEM features CMOS compatible control voltages to facilitate ease of use. With its integrated compact design, the TQF7059 minimizes radio footprint and component count while achieving industry leading output power and EVM rivaling complex discrete high power designs.

The TQF7059 is assembled in a Pb-Free, thin profile, 16 pad, 3 mm x 3 mm x 0.85 mm QFN package.

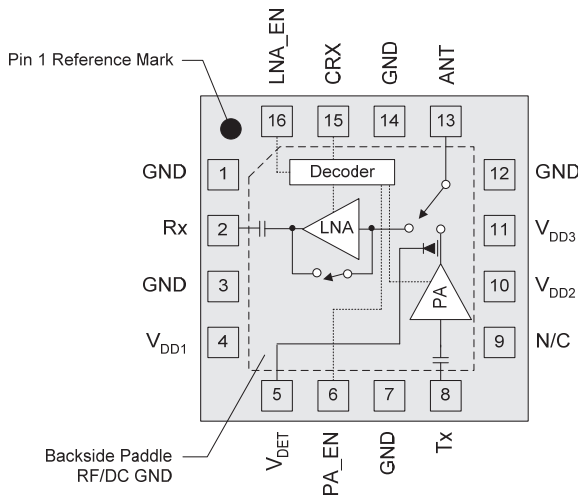


16 Pad 3 x 3 x 0.85 mm QFN Package

Product Features

- Fully Integrated, 802.11a/n/ac Front-end Module
- Internally Matched Input/Output
- Integrated Power Detector
- Temperature Compensated Bias Network
- Typ. Pout=+21.5 dBm at EVM=1.8% (-35 dB) 802.11ac/MCS9/VHT80 (+5 V)
- Typ. Pout=+23 dBm at EVM=3.0 % (-30 dB) 802.11n/MCS7/HT40 (+5 V)
- Supply Voltage +3.3 V to +5 V
- Leadless 3 x 3 x 0.85 mm QFN Package
- Lead Free, RoHS Compliant

Functional Block Diagram



Applications

- 802.11a/n/ac Wireless LAN Systems
- CPE (Set Top Box, routers, gateways)
- WiFi Access Points and Small Cells
- Telematics
- Gaming and Infotainment
- ISM applications 5–6 GHz

Ordering Information

| Part No. | Description |
|-------------|-------------------------------------|
| TQF7059 | 2500 Pieces on a 7" reel (standard) |
| TQF7059-PCB | Assembled Evaluation Board |

Absolute Maximum Ratings

| Parameter | Rating |
|----------------------------------|----------------|
| Storage Temperature | -40 to +150 °C |
| RF Input Power, CW, 50Ω, T=25 °C | +5 dBm |
| Case Temperature Survival | -40 to +100 °C |

Operation of this device outside the parameter ranges given above may cause permanent damage.

Recommended Operating Conditions

| Parameter | Min | Typ | Max | Units |
|--|-------|------|-------|-------|
| V _{DD1} , V _{DD2} , V _{DD3} | +3.15 | +5.0 | +5.25 | V |
| T _{AMB} | -30 | 25 | +85 | °C |
| T _j (for > 10 ⁶ hours MTTF) | | | 170 | °C |

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

Electrical Specifications – Overall Module

| Parameter | Conditions ⁽¹⁾ | Min | Typ | Max | Units |
|--|--|------|------|------------------|-------|
| Quiescent Current | P _{out} = -10 dBm, 11ac, MCS9, HT80 | | 180 | | mA |
| Operating Current | P _{out} = +20.5 dBm, 11ac, MCS9, HT80 | | 300 | | mA |
| PA Enable Control Voltage, V _{IH} | Input Voltage for High State | +1.8 | +3.0 | V _{DD1} | V |
| PA Enable Control Voltage, V _{IL} | Input Voltage for Low State | | 0 | +0.45 | V |
| Control Current, I _{IH} | | | | 100 | μA |
| TX Shutdown Current | | | 8 | | μA |
| TX Turn on/off time | 10 – 90% | | <0.4 | | μs |
| TX Rise/Fall time | 10 – 90% | | <0.4 | | μs |
| Thermal Resistance, θ _{jc} | Junction to backside paddle | | 27 | | °C/W |

Notes:

1. Test conditions unless otherwise noted: V_{DD1}, V_{DD2}, V_{DD3} = +5.0 V, Temp = +25°C.

Logic Truth Table

| 5 GHz FEM | PA_EN | LNA_EN | CRX |
|------------------|-------|--------|-----|
| Shutdown | 0 | 0 | 0 |
| Rx - Bypass Mode | 0 | 0 | 1 |
| RX- Normal Mode | 0 | 1 | 1 |
| TX Mode | 1 | 0 | 0 |

Electrical Specifications – Transmit (Tx)

| Parameter | Conditions | Min | Typ | Max | Units |
|--|-------------------------------------|------|------|------|---------|
| Operational Freq. Range | | 4900 | | 5925 | MHz |
| TX Gain | Small Signal | | 31 | | dB |
| | Pout = +21dBm | | 31 | | dB |
| Small Signal TX Gain Out of Band | 1600 – 1960 MHz | | -35 | | dB |
| | 3200 – 3900 MHz | | 2 | | |
| | 7000 MHz | | 20 | | |
| PA Noise Figure | Noise Figure | | 4 | | dB |
| TX Harmonics (2fo) | Pout = +25 dBm, 11a, 6 Mbps, 20 MHz | | -33 | | dBm/MHz |
| TX Harmonics (3fo) | Pout = +25 dBm, 11a, 6 Mbps, 20 MHz | | -37 | | dBm/MHz |
| ANT-RX Isolation | When TX is ON | | 45 | | dB |
| Spectral Emission Mask Margin Relative to 11ac standard 11ac, MCS0, HT20 | Pout = +25 dBm | | 3.6 | | dB |
| DEVM (11n/MCS7/HT40) | Pout = +23 dBm, 5150 – 5850 MHz | | -30 | | dB |
| DEVM (11ac/MCS9/VHT80) | Pout = +16 dBm, 5150 – 5850 MHz | | -37 | | dB |
| DEVM (11ac/MCS9/VHT80) | Pout = +20.5 dBm, 5150 – 5850 MHz | | -36 | | dB |
| Quiescent Current | No RF | | 180 | | mA |
| Operating Current | Pout = +20.5 dBm, 11ac, MCS9, VHT80 | | 300 | | mA |
| Detector Voltage | No RF | | 0.35 | | V |
| | Pout = +25 dBm | | 1.0 | | |

Notes:

- Test conditions unless otherwise noted: $V_{DD1}, V_{DD2}, V_{DD3} = +5.0\text{ V}$, Temp. = +25 °C, -45 dB EVM source, TQF7059-PCB

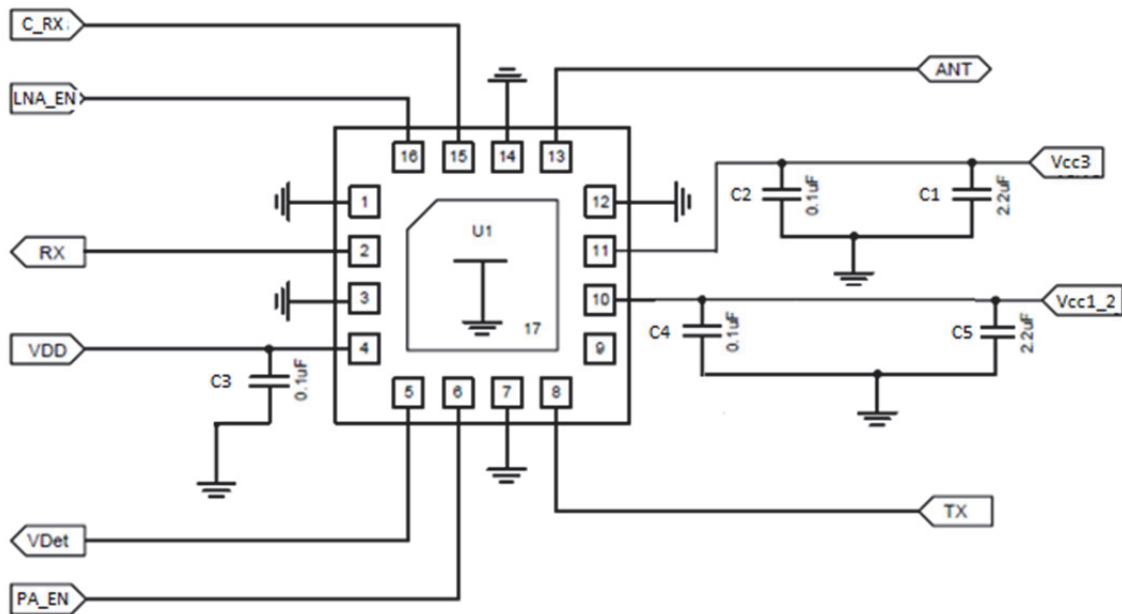
Electrical Specifications – Receive (Rx)

| Parameter | Conditions | Min | Typ | Max | Units |
|-------------------------|----------------------------|------|------|------|-------|
| Operating Frequency | | 4900 | | 5925 | MHz |
| RX Gain – Normal Mode | ANT to RX out | | 13 | | dB |
| RX Gain – Bypass Mode | ANT to RX out | | -7 | | dB |
| RX Flatness | Over entire, ANT to RX out | -1 | | 1 | |
| RX Noise Figure | Normal mode, ANT to RX out | | 2.1 | | dB |
| LNA Current | | | 9 | | mA |
| IIP3 – Normal Mode | At ANT port through LNA | | +4.0 | | dBm |
| IIP3 – Bypass Mode | At ANT port through LNA | | +23 | | dBm |
| RX Output Return Loss | RX output in RX mode | | 10 | | dB |
| RX ANT Port Return Loss | ANT port in RX mode | | 7 | | dB |
| RX Output Return Loss | RX output in Bypass mode | | 12 | | dB |
| RX ANT Port Return Loss | ANT port in Bypass mode | | 7 | | dB |

Notes:

- Test conditions unless otherwise noted: $V_{DD1}, V_{DD2}, V_{DD3} = +5.0\text{ V}$, Temp. = +25 °C, TQF7059-PCB

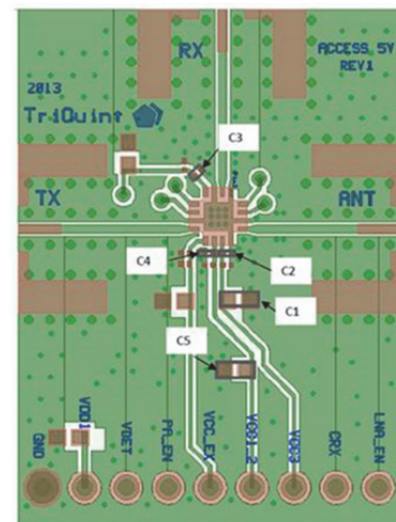
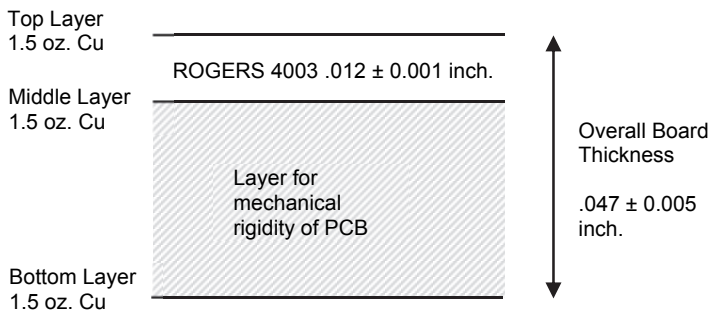
Application Circuit - TQF7059-PCB



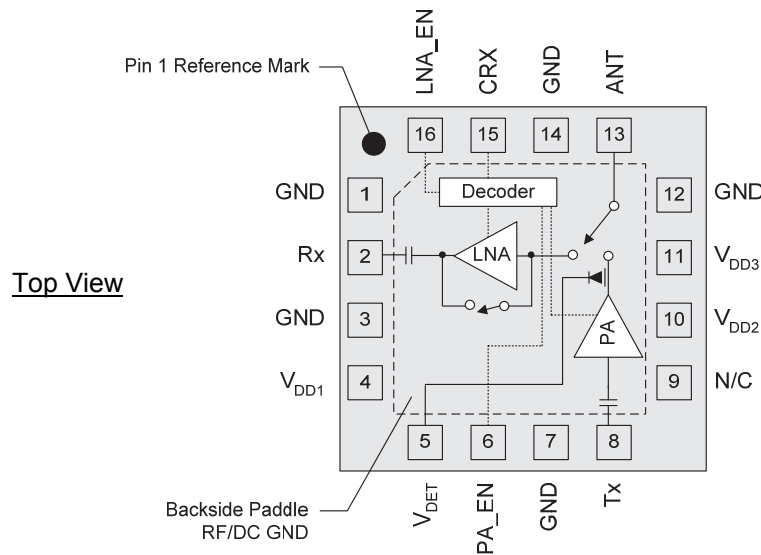
Bill of Material - TQF7059-PCB

| Ref Des | Value | Description | Manuf. | Part Number |
|------------|--------|---------------------------|---------|-------------|
| n/a | n/a | Printed Circuit Board | | |
| U1 | n/a | High Power WLAN 5GHz FEM | Qorvo | TQF7059 |
| C1, C5 | 2.2 uF | Capacitor, Chip, 0402, 5% | various | |
| C2, C3, C4 | 0.1 uF | Capacitor, Chip, 0201, 5% | various | |

Evaluation Board PCB Information



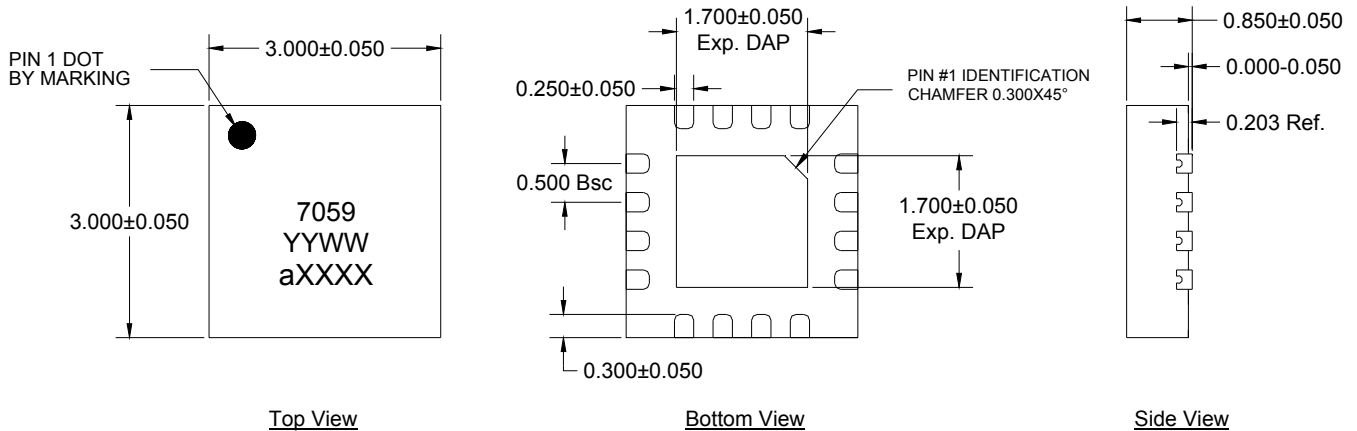
Pin Configuration and Description



| Pad No. | Label | Description |
|--------------|------------------|--|
| 1 | GND | Ground |
| 2 | Rx | Rx output, DC blocked RF I/O |
| 3 | GND | No internal connection. Recommended grounding this pin. |
| 4 | V _{DD1} | Supply pin for LNA, Logic & Bias circuits. |
| 5 | V _{DET} | Detector output voltage for 5 GHz PA |
| 6 | PA_EN | PA Enable |
| 7 | GND | No internal connection. Recommended grounding this pin. |
| 8 | Tx | 5 GHz Tx PA input, DC blocked RF I/O |
| 9 | NC | No internal connection. Recommended grounding this pin. |
| 10 | V _{DD2} | Supply pin for PA 1 st and 2 nd stage. |
| 11 | V _{DD3} | Supply pin for PA final stage. |
| 12 | GND | No internal connection. Recommended grounding this pin. |
| 13 | ANT | Antenna pin, DC blocked RF I/O |
| 14 | GND | No internal connection. Recommended grounding this pin. |
| 15 | CRX | Control pin. Refer to logic truth table on pg. 2 |
| 16 | LNA_EN | LNA Enable |
| Backside Pad | RF/DC GND | RF/DC ground. Use recommended via pattern to minimize inductance and thermal resistance. See PCB Mounting Pattern for suggested footprint. |

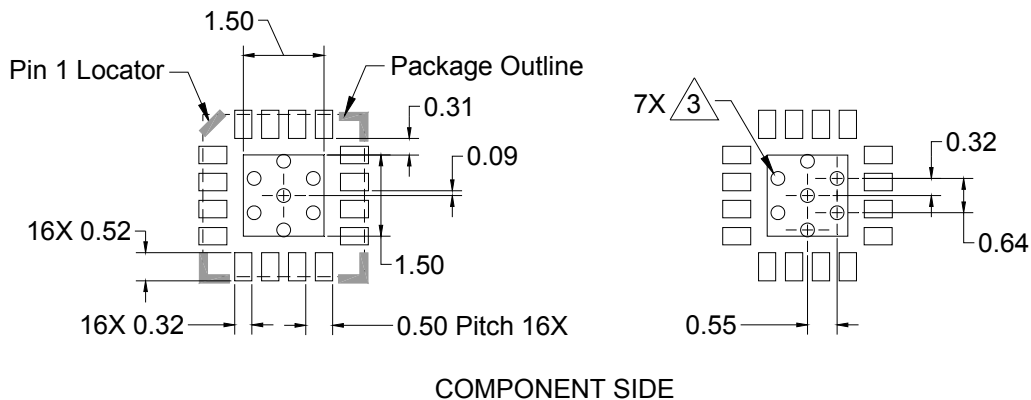
Package Marking and Dimensions

Marking: Product Identifier – “7059”
Date Code – YYWW
Lot Code – aXXXX



Notes:
1. All dimensions are in millimeters. Angles are in degrees.

PCB Mounting Pattern



Notes:

1. All dimensions are in millimeters. Angles are in degrees.
2. Use 1 oz. copper minimum for top and bottom layer metal.
3. Vias are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation. We recommend a 0.35mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of 0.25 mm (0.10").
4. Ensure good package backside paddle solder attach for reliable operation and best electrical performance.

Handling Precautions

| Parameter | Rating | Standard |
|----------------------------------|----------|--------------------------|
| ESD – Human Body Model (HBM) | Class 1B | ESDA / JEDEC JS-001-2012 |
| ESD – Charged Device Model (CDM) | Class C3 | JEDEC JESD22-C101F |
| MSL – Moisture Sensitivity Level | Level 1 | IPC/JEDEC J-STD-020 |



Caution!
ESD-Sensitive Device

Solderability

Compatible with both lead-free (260°C max. reflow temp.) and tin/lead (245°C max. reflow temp.) soldering processes. Solder profiles available upon request.

Contact plating: NiPdAu

RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- PFOS Free
- SVHC Free



Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

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Tel: 1-844-890-8163

Email: customer.support@qorvo.com

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- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
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